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FDPF770N15A N-Channel PowerTrench[®] MOSFET 150 V, 10 A, 77 m Ω

Features

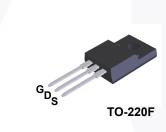
- $R_{DS(on)}$ = 60 m Ω (Typ.) @ V_{GS} = 10 V, I_D = 10 A
- Fast Switching Speed
- Low Gate Charge
- High Performance Trench Technology for Extremely Low $R_{\text{DS}(\text{on})}$
- High Power and Current Handling Capability
- RoHS Compliant

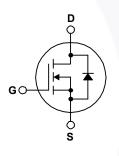
Description

This N-Channel MOSFET is produced using Fairchild Semiconductor's advanced PowerTrench[®] process that has been tailored to minimize the on-state resistance while maintaining superior switching performance.

Applications

- Consumer Appliances
- LED TV
- · Synchronous Rectification for ATX / Sever / Telecom PSU
- Uninterruptible Power Supply
- Micro Solar Inverter





Absolute Maximum Ratings T_C = 25°C unless otherwise noted.

Symbol		Parameter	FDPF770N15A	Unit V	
V _{DSS}	Drain to Source Voltage		150		
V _{GSS}	Cata to Source Voltage	- DC	±20	V	
	Gate to Source Voltage	- AC (f > 1 Hz)	±30	v	
ID	Drain Current	- Continuous (T _C = 25°C,Silicon Limited)	10	- A	
	Drain Current	- Continuous (T _C = 100 ^o C,Silicon Limited)	7		
I _{DM}	Drain Current	- Pulsed (Note 1)	40	А	
E _{AS}	Single Pulsed Avalanche Energ	35	mJ		
dv/dt	Peak Diode Recovery dv/dt	6.0	V/ns		
P _D	Dower Discinction	$(T_{\rm C} = 25^{\rm o}{\rm C})$	21	W	
	Power Dissipation	- Derate Above 25°C	0.17	W/ºC	
T _J , T _{STG}	Operating and Storage Temperation	-55 to +150	°C		
TL	Maximum Lead Temperature fo	r Soldering, 1/8" from Case for 5 Seconds	300	°C	

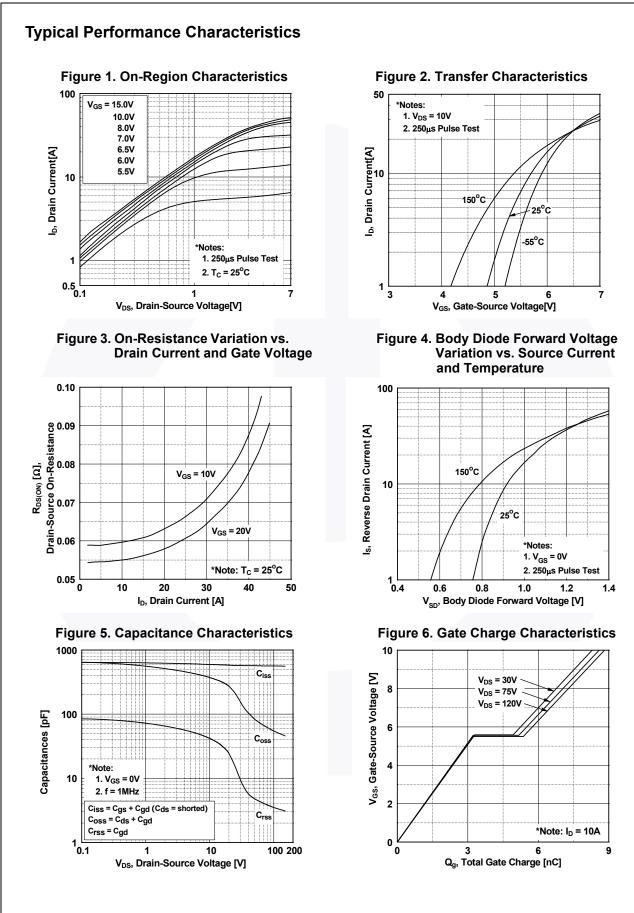
Thermal Characteristics

Symbol	Parameter	FDPF770N15A	Unit
$R_{ ext{ heta}JC}$	Thermal Resistance, Junction to Case, Max.	5.9	°C/W
R_{\thetaJA}	Thermal Resistance, Junction to Ambient, Max.	62.5	0/00

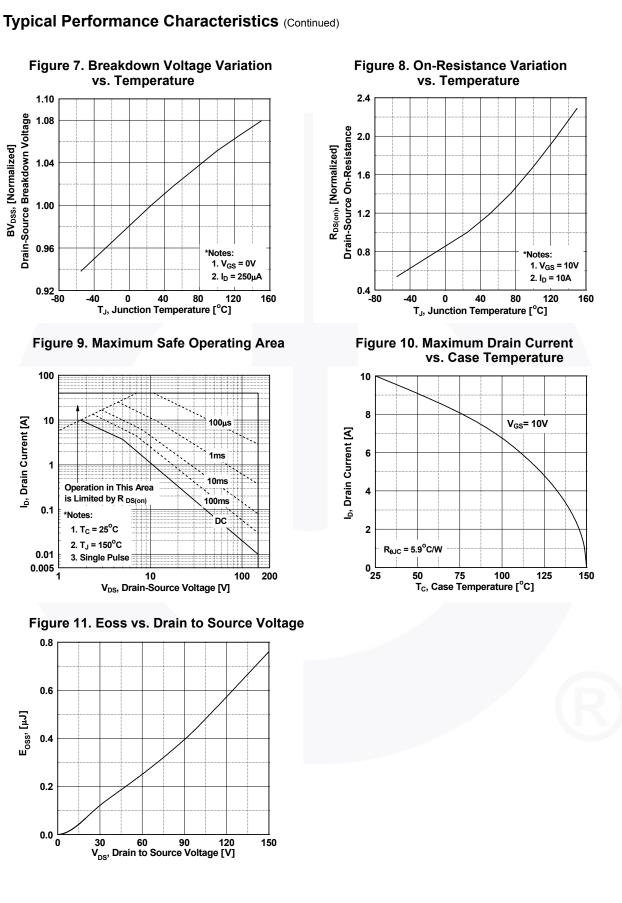
March 2015

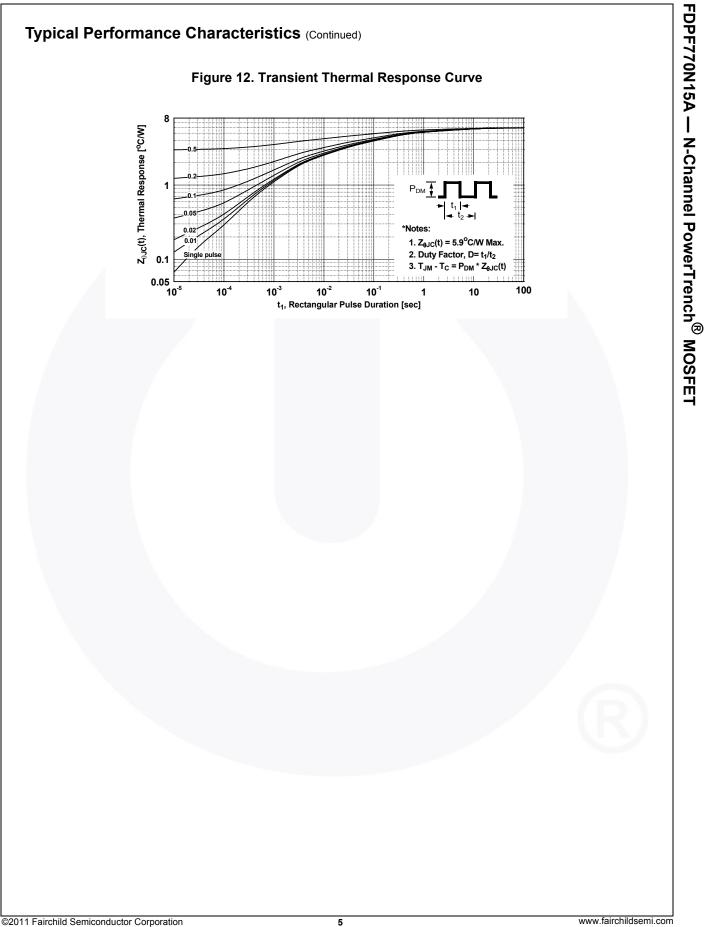
)N15A	FDPF770N15A		Packing Method	Reel Size	Э 🛛	Tape Width	Qu	antity
	1	TO-220F	Tube	N/A		N/A	50) units
Chara	cteristics T _C = 2	25°C unless o	therwise noted.					
Parameter			Test Conditions		Min.	Тур.	Max.	Unit
teristics								
	Source Breakdown Vol	tage	$I_{\rm p} = 250 \mu A V_{\rm eq} = 0 V$		150	_		V
Breakdown Voltage Temperature Coefficient			$I_D = 250 \ \mu\text{A}, \ V_{GS} = 0.7$ $I_D = 250 \ \mu\text{A}, \ \text{Referenced to } 25^{\circ}\text{C}$		100			
		•			-	0.1	-	V/ºC
Zero Gate Voltage Drain Current			V _{DS} = 120 V, V _{GS} = 0 V		-	-	1	_
		IT				-	500	μA
Gate to Body Leakage Current			V _{GS} = ±20 V, V _{DS} = 0 V			-	±100	nA
								-
Gate Threshold Voltage			$V_{GS} = V_{DS}$, $I_D = 250 \ \mu A$			-	4.0	V
	Static Drain to Source On Resistance					60	77	mΩ
Forward	Fransconductance		V _{DS} = 10 V, I _D = 10 A		-	15	-	S
haracter	istics							
-					-	575	765	pF
Output Ca	apacitance			, = 0 V,	-	64	85	pF
Reverse 7	e Transfer Capacitance				-	3.9	-	pF
Energy R	Energy Related Output Capacitance		V_{DS} = 75 V, V_{GS} = 0 V			113	-	pF
Total Gate	· · ·				-	8.6	11.2	nC
Gate to S	ource Gate Charge		$V_{DS} = 75 V, I_D = 10 A,$ $V_{GS} = 10 V$			3.2	-	nC
Gate Cha	rge Threshold to Plate	au			-	1.2	-	nC
Gate to D	rain "Miller" Charge			(Note 4)	-	1.9	-	nC
Equivaler	it Series Resistance (0	G-S)	f = 1 MHz		-	0.5	-	Ω
Characte	ristics							
1						12	34	ns
Turn-On F	,		V _{DD} = 75 V, I _D = 10 A,		-	8	26	ns
			V _{GS} = 10 V, R _G = 4.7 Ω			15	40	ns
Turn-Off F	all Time		(Note 4		7 -	3	16	ns
	Characteristics	I					1	1
			Forward Current		-		10	А
					-	_		A
					-	-		V
	Recovery Time			- = 75 \/	-	59	-	ns
	Recovery Charge		V_{GS} = 0 V, I_{SD} = 10 A, V_{DD} = 75 V, dI _F /dt = 100 A/µs		-	124	-	nC
	Drain to S Breakdow Coefficier Zero Gate Gate to B teristics Gate Thre Static Dra Forward Forward Naracter Input Cap Output Ca Reverse Total Gate Gate to S Gate to S Gate to S Gate to S Gate to S Gate to D Equivalen Turn-On E Turn-On F Turn-Off E Turn-Off E Turn-Off E Maximum Maximum Drain to S	Drain to Source Breakdown Vol Breakdown Voltage Temperatur Coefficient Zero Gate Voltage Drain Currer Gate to Body Leakage Current teristics Gate Threshold Voltage Static Drain to Source On Resis Forward Transconductance haracteristics Input Capacitance Output Capacitance Energy Related Output Capacita Total Gate Charge at 10V Gate to Source Gate Charge Gate Charge Threshold to Plate Gate to Drain "Miller" Charge Equivalent Series Resistance (C Characteristics Turn-On Delay Time Turn-On Rise Time Turn-Off Fall Time ce Diode Characteristics Maximum Continuous Drain to S Maximum Pulsed Drain to Source Drain to Source Diode Forward	Drain to Source Breakdown Voltage Breakdown Voltage Temperature Coefficient Zero Gate Voltage Drain Current Gate to Body Leakage Current teristics Gate Threshold Voltage Static Drain to Source On Resistance Forward Transconductance haracteristics Input Capacitance Output Capacitance Reverse Transfer Capacitance Energy Related Output Capacitance Total Gate Charge at 10V Gate to Drain "Miller" Charge Equivalent Series Resistance (G-S) Characteristics Turn-On Delay Time Turn-Off Delay Time Turn-Off Fall Time Ce Diode Characteristics Maximum Continuous Drain to Source Diode Maximum Pulsed Drain to Source Diode Forward Voltage	Drain to Source Breakdown Voltage $I_D = 250 \ \mu\text{A}$, $V_{GS} = 0 \ V$ Breakdown Voltage Temperature Coefficient $I_D = 250 \ \mu\text{A}$, ReferencedZero Gate Voltage Drain Current $V_{DS} = 120 \ V, V_{GS} = 0 \ V$ Gate to Body Leakage Current $V_{DS} = 120 \ V, V_{DS} = 0 \ V$ teristics $V_{GS} = \pm 20 \ V, V_{DS} = 0 \ V$ Gate Threshold Voltage $V_{GS} = \pm 20 \ V, V_{DS} = 0 \ V$ teristics $V_{GS} = \pm 20 \ V, V_{DS} = 0 \ V$ Gate Threshold Voltage $V_{GS} = \pm 20 \ V, V_{DS} = 0 \ V$ teristics $V_{GS} = 10 \ V, I_D = 10 \ A$ Static Drain to Source On Resistance $V_{GS} = 10 \ V, I_D = 10 \ A$ Forward Transconductance $V_{DS} = 75 \ V, V_{GS} = 0 \ V, f = 1 \ MHz$ Input Capacitance $V_{DS} = 75 \ V, V_{GS} = 0 \ V, f = 1 \ MHz$ Reverse Transfer Capacitance $V_{DS} = 75 \ V, V_{GS} = 0 \ V$ Gate to Source Gate Charge $V_{DS} = 75 \ V, I_D = 10 \ A, V_{GS} = 10 \ V$ Gate to Source Gate Charge $V_{DS} = 75 \ V, I_D = 10 \ A, V_{GS} = 10 \ V$ Gate to Drain "Miller" ChargeEquivalent Series Resistance (G-S)Turn-On Delay Time $V_{DD} = 75 \ V, I_D = 10 \ A, V_{GS} = 10 \ V, R_G = 4.7 \ \Omega$ Turm-Off Delay Time $V_{GS} = 10 \ V, R_G = 4.7 \ \Omega$ Turm-Off Fall Time $V_{GS} = 0 \ V, I_{SD} = 10 \ A, V_{GS} = 10 \ V, R_G = 0 \ V, I_S = 10 \ A, V_{GS} = 10 \ V, R_G = 4.7 \ \Omega$ Maximum Continuous Drain to Source Diode Forward CurrentMaximum Pulsed Drain to Source Diode Forward CurrentMaximum Pulsed Drain to Source Diode Forward CurrentMaximum Pulsed Drain to Source Diode Forward Current <td>Drain to Source Breakdown VoltageID250 μA, VGS = 0 VBreakdown Voltage Temperature CoefficientID= 250 μA, Referenced to 25°CZero Gate Voltage Drain Current$V_{DS} = 120 V, V_{GS} = 0 V$Gate to Body Leakage Current$V_{DS} = 120 V, V_{C} = 125°C$Gate Threshold Voltage$V_{GS} = ±20 V, V_{DS} = 0 V$teristicsGate Threshold Voltage$V_{GS} = 10 V, I_D = 10 A$Static Drain to Source On Resistance$V_{GS} = 10 V, I_D = 10 A$Forward Transconductance$V_{DS} = 75 V, V_{GS} = 0 V, I_D = 10 A$haracteristicsInput Capacitance$V_{DS} = 75 V, V_{GS} = 0 V, I_D = 10 A$Couput Capacitance$V_{DS} = 75 V, V_{GS} = 0 V, I_D = 10 A, V_{DS} = 75 V, V_{GS} = 0 V, I_D = 10 A, V_{DS} = 75 V, I_D = 10 A, V_{DS} = 75 V, I_D = 10 A, V_{DS} = 75 V, I_D = 10 A, V_{GS} = 10 V, R_G = 4.7 \Omega$Turn-On Blay TimeV_DD = 75 V, I_D = 10 A, V_{GS} = 10 V, R_G = 4.7 \OmegaTurn-Off Fall TimeV_{OS} = 10 V, R_G = 4.7 \OmegaTurn-Off Fall TimeV_{OS} = 0 V, I_{SD} = 10 A, V_{GS} = 0 V, I_{SD} = 10 A, V_{GS} = 0 V, I_{SD} = 10 A, V_{GS} = 0 V, I_{SD} = 10 A</td> <td>$\begin{tabular}{ c$</td> <td>$\begin{tabular}{ c$</td> <td>$\begin{tabular}{ c c c c c c } \hline Prain to Source Breakdown Voltage Inp = 250 \ \mu A, V_{GS} = 0 \ V & 150 & - & - & \\ \hline Breakdown Voltage Temperature Coefficient & V_{DS} = 120 \ V, V_{GS} = 0 \ V & - & - & 1 & \\ \hline V_{DS} = 120 \ V, \ V_{GS} = 0 \ V & - & - & 1 & \\ \hline V_{DS} = 120 \ V, \ V_{CS} = 10 \ V & - & - & 1 & \\ \hline V_{DS} = 120 \ V, \ V_{CS} = 10 \ V & - & - & \pm 100 \\ \hline \end{tabular}$</td>	Drain to Source Breakdown VoltageID250 μA, VGS = 0 VBreakdown Voltage Temperature CoefficientID= 250 μA, Referenced to 25°CZero Gate Voltage Drain Current $V_{DS} = 120 V, V_{GS} = 0 V$ Gate to Body Leakage Current $V_{DS} = 120 V, V_{C} = 125°C$ Gate Threshold Voltage $V_{GS} = ±20 V, V_{DS} = 0 V$ teristicsGate Threshold Voltage $V_{GS} = 10 V, I_D = 10 A$ Static Drain to Source On Resistance $V_{GS} = 10 V, I_D = 10 A$ Forward Transconductance $V_{DS} = 75 V, V_{GS} = 0 V, I_D = 10 A$ haracteristicsInput Capacitance $V_{DS} = 75 V, V_{GS} = 0 V, I_D = 10 A$ Couput Capacitance $V_{DS} = 75 V, V_{GS} = 0 V, I_D = 10 A, V_{DS} = 75 V, V_{GS} = 0 V, I_D = 10 A, V_{DS} = 75 V, I_D = 10 A, V_{DS} = 75 V, I_D = 10 A, V_{DS} = 75 V, I_D = 10 A, V_{GS} = 10 V, R_G = 4.7 \Omega$ Turn-On Blay TimeV_DD = 75 V, I_D = 10 A, V_{GS} = 10 V, R_G = 4.7 \OmegaTurn-Off Fall TimeV_{OS} = 10 V, R_G = 4.7 \OmegaTurn-Off Fall TimeV_{OS} = 0 V, I_{SD} = 10 A, V_{GS} = 0 V, I_{SD} = 10 A, V_{GS} = 0 V, I_{SD} = 10 A, V_{GS} = 0 V, I_{SD} = 10 A	$\begin{tabular}{ c $	$\begin{tabular}{ c $	$\begin{tabular}{ c c c c c c } \hline Prain to Source Breakdown Voltage Inp = 250 \ \mu A, V_{GS} = 0 \ V & 150 & - 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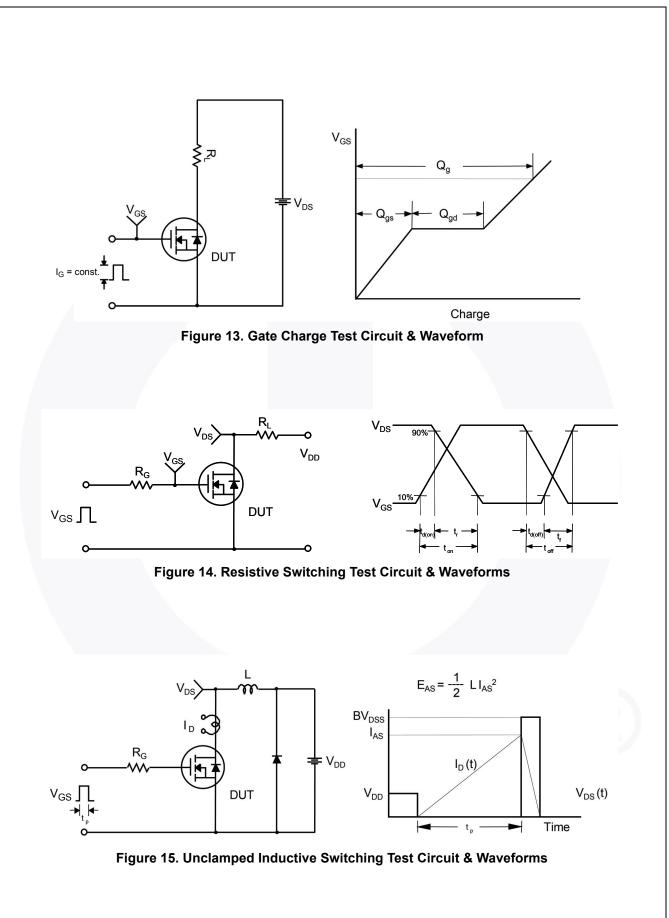




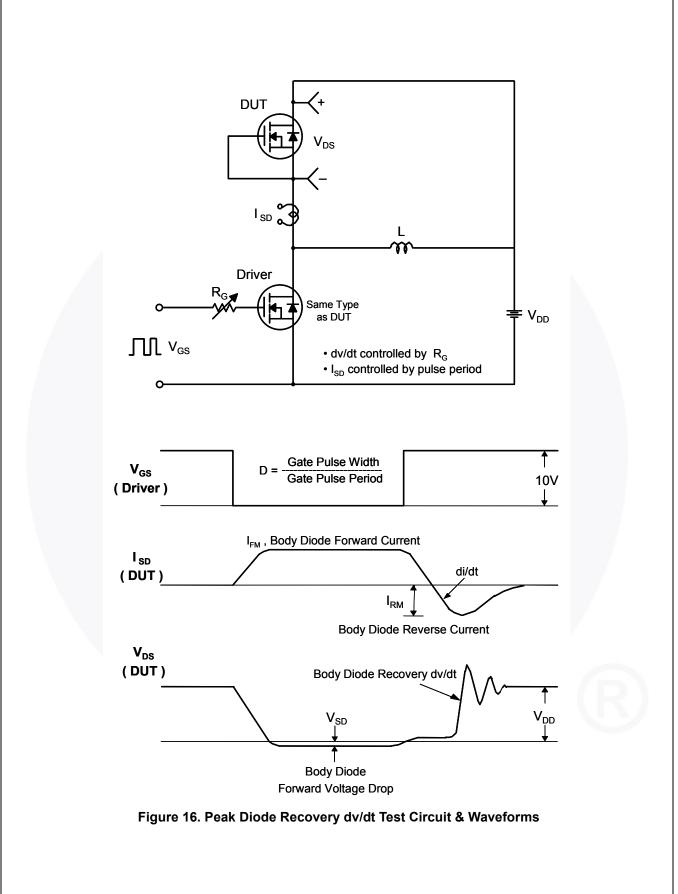
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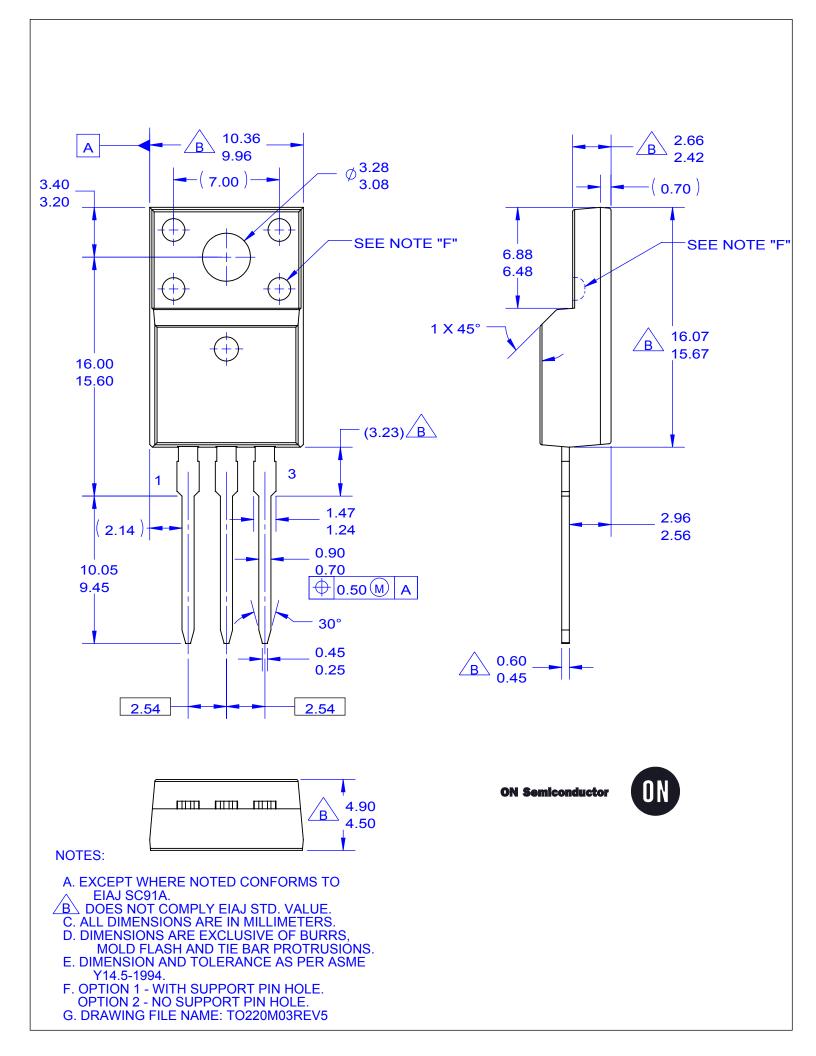




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